What is claimed is:

1. A method of encapsulating a display element, comprising steps of:

providing an organic light emitting diode or a plastic light emitting diode, comprising a luminescent body formed on a glass substrate and a glass cap with a rib structure formed on the bottom surface thereof;

coating a sealing layer of frit on the rim of the glass cap and surrounding the rib structure;

providing a pedestal on which the display element is placed;

providing a pressing plate disposed on the display element;

providing a high-power beam penetrating the glass cap to focus on the sealing layer so as to sinter the frit; and

applying pressure on the pedestal and the pressing plate.

2. The method of encapsulating a display element according to claim 1, wherein the pedestal and the pressing plate are of metal materials with good thermal conductivity.

3. The method of encapsulating a display element according to claim 1, wherein the high-power beam is a laser beam.

4. The method of encapsulating a display element according to claim 1, wherein the laser beam has a wavelength exceeding 550nm.

5. The method of encapsulating a display element according to claim 1, wherein the high-power beam is an infrared ray.

6. The method of encapsulating a display element according to claim 1, wherein the infrared ray has a wavelength exceeding 800nm.

7. The method of encapsulating a display element according to claim 1, wherein the rib structure is frit.

8. The method of encapsulating a display element according to claim 1, wherein the rib structure is of ceramic materials.

9. The method of encapsulating a display element according to claim 1, wherein the luminescent body is laminated with at least an anode layer, an organic luminescent layer and a cathode layer.